PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WEI-CHENG WU	06/06/2014
WEI MIN CHAN	06/06/2014
YEN-HUEI CHEN	06/06/2014
HUNG-JEN LIAO	06/06/2014
PING-WEI WANG	06/06/2014

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15012970

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	T5057-1044A	
NAME OF SUBMITTER:	RANDY A. NORANBROCK	
SIGNATURE:	/Randy A. Noranbrock/	
DATE SIGNED:	02/02/2016	

Total Attachments: 1

PATENT REEL: 037641 FRAME: 0631 source=EfiledAssgn#page1.tif

PATENT REEL: 037641 FRAME: 0632

ASSIGNMENT

In consideration of the premises and other	r good and valuable	consideration in	hand paid, t	he receipt an	d sufficiency of
which is hereby acknowledged, the undersigned,	-		•	•	v

1) Wei-Cheng WU

4) Hung-Jen LIAO

2) Wei Min CHAN

5) Ping-Wei WANG

3) Yen-Huei CHEN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., <u>having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.</u>

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

STATIC RANDOM ACCESS MEMORY AND METHOD OF USING THE SAME

(a)	for which an application for United States Letters Patent was filed on 2014-06-18 , a United States Patent Application No. 14/308,065 ; or	md identified	by
(b)	for which an application for United States Letters Patent was executed on,		

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Wei-Cheng Wu	2014/6/6
Name: Wei-Cheng WU	Date:
2) Wei Min Chan	2014/6/6
Name: Wei Min CHAN	Date:
3) Yen-Huei CHEN	~14/6/6
Name: Yen-Huei CHEN	Date:
4) Hung-Jen Cian Name: Hung-Jen LIAO	6/6/2014
Name: Hung-Jen LIAO	Date:
5) By Wei Wy	6/6/1x
Name: Pino-Wei WANG	Date

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RECORDED: 02/02/2016